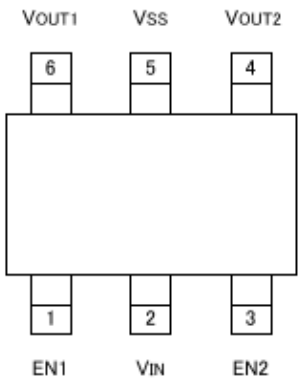
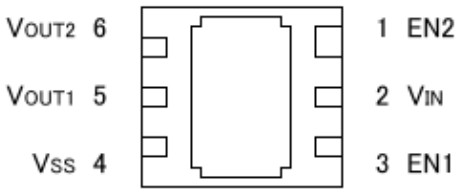


PIN CONFIGURATION



SOT-26
(TOP VIEW)



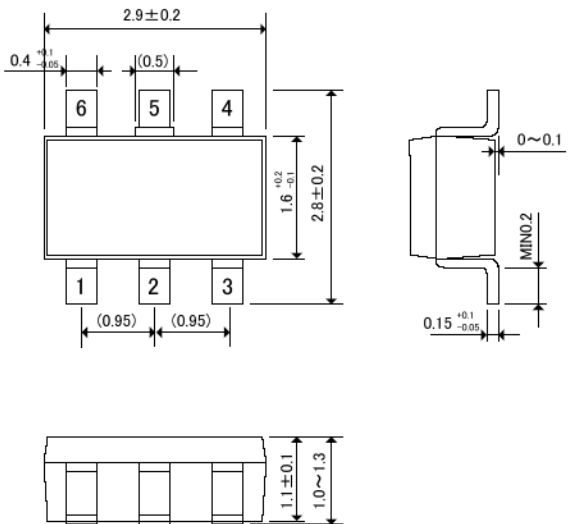
USP-6C
(BOTTOM VIEW)

*The dissipation pad for the USP-6C package should be solder-plated in recommended mount pattern and metal masking so as to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the V_{SS} (No. 4) pin.

PACKAGING INFORMATION

● SOT-26

(unit : mm)



● USP-6C

(unit : mm)

